

RELIABILITY REPORT  
FOR  
MAX6340UK16+  
PLASTIC ENCAPSULATED DEVICES

November 19, 2008

**MAXIM INTEGRATED PRODUCTS**

120 SAN GABRIEL DR.  
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<b>Approved by</b>
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Quality Assurance
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## Conclusion

The MAX6340UK16+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX6340/MAX6421 - MAX6426 low-power microprocessor supervisor circuits monitor system voltages from 1.6V to 5V. These devices perform a single function: they assert a reset signal whenever the VCC supply voltage falls below its reset threshold. The reset output remains asserted for the reset timeout period after VCC rises above the reset threshold. The reset timeout is externally set by a capacitor to provide more flexibility. The MAX6421/MAX6424 have an active-low, push-pull reset output. The MAX6422 has an active-high, push-pull reset output and the MAX6340/MAX6423/MAX6425/MAX6426 have an active-low, open-drain reset output. The MAX6421/MAX6422/MAX6423 are offered in 4-pin SC70 or SOT143 packages. The MAX6340/MAX6424/MAX6425/MAX6426 are available in 5-pin SOT23-5 packages.

## II. Manufacturing Information

A. Description/Function:	Low-Power, SC70/SOT $\mu$ P Reset Circuits with Capacitor-Adjustable Reset Timeout Delay
B. Process:	B8
C. Number of Device Transistors:	
D. Fabrication Location:	Texas
E. Assembly Location:	Carsm Malaysia, ISPL Philippines, Hana Thailand, UTL Thailand, Unisem Malaysia
F. Date of Initial Production:	October 26, 2002

## III. Packaging Information

A. Package Type:	5-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-0074
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	324.3°C/W
K. Single Layer Theta Jc:	82°C/W

## IV. Die Information

A. Dimensions:	36 X 36 mils
B. Passivation:	$\text{Si}_3\text{N}_4/\text{SiO}_2$ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	$\text{SiO}_2$
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)  
Bryan Preeshl (Managing Director of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are pending. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 135 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 8.0 \times 10^{-9}$$

$\lambda = 8.0$  F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the B8 Process results in a FIT Rate of 2.71 @ 25C and 17.30 @ 55C (0.8 eV, 60% UCL)

### B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

### C. E.S.D. and Latch-Up Testing

The MS60-9 die type has been found to have all pins able to withstand a HBM transient pulse of +/-500 V per JEDEC JESD22A114D and a CDM transient pulse of +/-750V. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX6340UK16+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	135	0
<b>Moisture Testing</b> (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress</b> (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data